

**Electronic Patent Application Fee Transmittal**

<b>Application Number:</b>	10507325			
<b>Filing Date:</b>	10-Sep-2004			
<b>Title of Invention:</b>	Method and apparatus for processing brittle material			
<b>First Named Inventor/Applicant Name:</b>	Hideki Morita			
<b>Filer:</b>	Lee Cheng/Maki Huffman			
<b>Attorney Docket Number:</b>	APA-0216			
Filed as Large Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
<b>Extension-of-Time:</b>				
Extension - 3 months with \$490 paid	1253	1	620	620

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Miscellaneous:</b>				
Request for continued examination	1801	1	810	810
<b>Total in USD (\$)</b>				<b>1430</b>